



# 100% Material Declaration Data Sheet for 7 Series SBG484

PK600 (v1.0) February 15, 2013

**Average Weight: 1.4728g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.237468</b>	<b>16.123</b>
	Silicon (Si)	7440-21-3	100.00	basis	0.237468	
<b>Solder Bump</b>					<b>0.011261</b>	<b>0.765</b>
	Tin (Sn)	7440-31-5	63.00	basis	0.007094	
	Lead (Pb)	7439-92-1	37.00	basis	0.004167	
<b>Underfill</b>					<b>0.035000</b>	<b>2.376</b>
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	basis	0.007000	
	Phenolic resin	trade secret	15.00	basis	0.005250	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	basis	0.001750	
	Amine type accelerator	trade secret	5.00	basis	0.001750	
	Silicon dioxide	60676-86-0	51.50	basis	0.018025	
	Carbon black	1333-86-4	1.00	basis	0.000350	
	Additives	trade secret	2.50	Additive	0.000875	
<b>Solder Ball</b>					<b>0.233980</b>	<b>15.887</b>
	Sn	7440-31-5	96.50	Main material	0.225791	
	Ag	7440-22-4	3.00	Main material	0.007019	
	Cu	7440-50-8	0.50	Main material	0.001170	
<b>Substrate</b>					<b>0.955101</b>	<b>64.849</b>
	Copper (Cu)	7440-50-8	36.72		0.350689	
	Tin (Sn)	7440-31-5	1.38		0.013140	
	Lead (Pb)	7439-92-1	0.41		0.003876	
	Silver (Ag)	7440-22-4	0.02		0.000203	
	BT Core	trade secret	47.75		0.456088	
	ABF	trade secret	11.22		0.107127	
	Solder Mask	trade secret	2.51		0.023978	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
02/15/2013	1.0	Initial Xilinx release.

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